

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6784386

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHING-SHENG CHENG	04/23/2019
CHIA-WEN WENG	04/23/2019
RECEIVING PARTY DATA	
Name:	Hewlett-Packard Development Company, L.P.
Street Address:	10300 Energy Drive
City:	Spring
State/Country:	TEXAS
Postal Code:	77389
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17418913
CORRESPONDENCE DATA	
Fax Number:	(970)778-4063
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(541)360-4450
Email:	ipa.mail@hp.com
Correspondent Name:	HP INC.
Address Line 1:	3390 E. HARMONY ROAD MS 35
Address Line 4:	FORT COLLINS, COLORADO 80528
ATTORNEY DOCKET NUMBER:	86034210
NAME OF SUBMITTER:	CARRIE A. MILANO
SIGNATURE:	/Carrie A. Milano/
DATE SIGNED:	06/28/2021
Total Attachments: 2	
source=86034210 Executed Assignment#page1.tif	
source=86034210 Executed Assignment#page2.tif	

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 85719917

ASSIGNMENT OF PATENT APPLICATION

I, the undersigned, for good and valuable consideration, the receipt of which is hereby acknowledged, agree to assign and transfer and hereby assign and transfer to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Spring, Texas, (hereinafter "HPDC"), its successors, and its assigns, my entire right, title, and interest, including all rights of priority, in, to, and under an application for patent entitled (English-language title in parentheses if said application for patent is in another language):

SENSOR DEVICES ATTACHABLE TO ELECTRONIC DEVICES

Filing Date: 25 Apr 2019 Application No.: PCT/US2019/029203 Patent Office: US

the subject matter, including any and all inventions, improvements, and discoveries, set forth in said application for patent (as used herein "patent" refers to any form of intellectual property protection including, without limitation, invention rights, utility patent rights, design rights, and utility model rights) (hereinafter "inventions"); any and all existing and future applications for patent of any country or region or under any international agreement for any of said inventions (including, without limitation, said application for patent, any and all applications for patent directly or indirectly claiming priority to or benefit of any application for patent for any of said inventions, any and all applications for patent from which any application for patent for any of said inventions directly or indirectly claims priority or benefit, and any and all continuation applications of, continuation-in-part applications (hereinafter CIPs) of, divisional applications of, national-phase applications of, regional-phase applications of, renewals of, and substitutes for any application for patent for any of said inventions) (hereinafter "Applications for Patent"); any and all patents which may be granted on or as a result of said Applications for Patent (hereinafter "Patents"); and any and all reissues, reexaminations, and extensions of said Applications for Patent or said Patents.

I HEREBY represent that I convey my full rights in all countries and regions and under all international agreements to the entire right, title, and interest herein assigned and transferred, and that I have not executed and will not execute any agreement in conflict herewith;

AND I HEREBY authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to file said Applications for Patent in its name or in my name in any country or region or under any international agreement, and further authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to insert the filing date, application number, and patent office of said application for patent, now identified by the Record ID and title set forth above, when known to them;

AND I HEREBY authorize and request the officials of all countries and regions and under all international agreements whose duty it is to issue patents, to issue to HPDC, its successors, or its assigns, as assignee of my entire right, title, and interest, said Patents, in accordance with the terms of this assignment and transfer;

AND I HEREBY covenant and agree that I will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title in said inventions, Applications for Patent, and Patents, to HPDC, its successors, or its assigns; communicate to HPDC, its successors, its assigns, its nominees, or its legal representatives, all known facts respecting said inventions, Applications for Patent, and Patents; testify in any legal or administrative proceedings and sign all lawful papers (including, without limitation, divisional applications, continuation applications, CIPs, and reissue applications) relating to said inventions, Applications for Patent, and Patents; and make all rightful oaths and declarations and generally to do everything possible to aid HPDC, its successors, its assigns, its nominees, and its legal representatives to obtain, maintain, and enforce, for its or their own benefit, proper intellectual property protection for said inventions, Applications for Patent, and Patents, provided the expenses which may be incurred by me in lending such cooperation and assistance are paid by HPDC, its successors, its assigns, its nominees, or its legal representatives.

IN WITNESS WHEREOF, I hereunto set my hand and seal:

Ching-Sheng Cheng
Inventor's Signature

25 Day 4 Month 2019 Year

Ching-Sheng Cheng
Given (First and Middle) Name(s) Family Name

HP Inc.
3390 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 85719917

ASSIGNMENT OF PATENT APPLICATION

I, the undersigned, for good and valuable consideration, the receipt of which is hereby acknowledged, agree to assign and transfer and hereby assign and transfer to HEWLETT-PACKARD DEVELOPMENT COMPANY, L.P., a Texas Limited Partnership having its principal place of business in Spring, Texas, (hereinafter "HPDC"), its successors, and its assigns, my entire right, title, and interest, including all rights of priority, in, to, and under an application for patent entitled (English-language title in parentheses if said application for patent is in another language):

SENSOR DEVICES ATTACHABLE TO ELECTRONIC DEVICES

Filing Date: 25 Apr 2019 Application No.: PCT/US2019/029203 Patent Office: US

the subject matter, including any and all inventions, improvements, and discoveries, set forth in said application for patent (as used herein "patent" refers to any form of intellectual property protection including, without limitation, invention rights, utility patent rights, design rights, and utility model rights) (hereinafter "Inventions"); any and all existing and future applications for patent of any country or region or under any international agreement for any of said Inventions (including, without limitation, said application for patent, any and all applications for patent directly or indirectly claiming priority to or benefit of any application for patent for any of said Inventions, any and all applications for patent from which any application for patent for any of said Inventions directly or indirectly claims priority or benefit, and any and all continuation applications of, continuation-in-part applications (hereinafter CIPs) of, divisional applications of, national-phase applications of, regional-phase applications of, renewals of, and substitutes for any application for patent for any of said Inventions) (hereinafter "Applications for Patent"); any and all patents which may be granted on or as a result of said Applications for Patent (hereinafter "Patents"); and any and all reissues, reexaminations, and extensions of said Applications for Patent or said Patents.

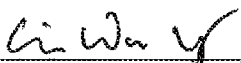
I HEREBY represent that I convey my full rights in all countries and regions and under all international agreements to the entire right, title, and interest herein assigned and transferred, and that I have not executed and will not execute any agreement in conflict herewith;

AND I HEREBY authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to file said Applications for Patent in its name or in my name in any country or region or under any international agreement, and further authorize HPDC, its successors, its assigns, its nominees, and its legal representatives to insert the filing date, application number, and patent office of said application for patent, now identified by the Record ID and title set forth above, when known to them;

AND I HEREBY authorize and request the officials of all countries and regions and under all international agreements whose duty it is to issue patents, to issue to HPDC, its successors, or its assigns, as assignee of my entire right, title, and interest, said Patents, in accordance with the terms of this assignment and transfer;

AND I HEREBY covenant and agree that I will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title in said Inventions, Applications for Patent, and Patents, to HPDC, its successors, or its assigns; communicate to HPDC, its successors, its assigns, its nominees, or its legal representatives, all known facts respecting said Inventions, Applications for Patent, and Patents; testify in any legal or administrative proceedings and sign all lawful papers (including, without limitation, divisional applications, continuation applications, CIPs, and reissue applications) relating to said Inventions, Applications for Patent, and Patents; and make all rightful oaths and declarations and generally to do everything possible to aid HPDC, its successors, its assigns, its nominees, and its legal representatives to obtain, maintain, and enforce, for its or their own benefit, proper intellectual property protection for said Inventions, Applications for Patent, and Patents, provided the expenses which may be incurred by me in lending such cooperation and assistance are paid by HPDC, its successors, its assigns, its nominees, or its legal representatives.

IN WITNESS WHEREOF, I hereunto set my hand and seal:


Inventor's Signature

23 April 2019
Day Month Year

Chia-Wen Weng

Given (First and Middle) Name(s) Family Name

Rev 8/2016 (HPDC Assignment)

RECORDED: 06/28/2021

PATENT
REEL: 056683 FRAME: 0598